Dave Palmer: The best advice I received was from a past president of CPMT, Skip Porter. He called me up one day when I still was struggling finding a place at Sandia. He said there were many ways to help the Society. He gave me a list of openings and asked me to pick 2. I was most comfortable with newsletter editing and with Rules of Order. So I became editor and keeper of the Constitution. So find a list and pick at least one.

Once you are a real volunteer and not just an attendee, the opportunities to continue education and to publish will be obvious.

I'm afraid I am beyond help from our Society members. I am getting ready to retire and everyone in the Society, especially those that have retired from several employers, do not seem to know how to retire. In contrast, it is good to see that former president Rao Tummala has played some golf in many parts of the world after decades of packaging technology concentration. Most packaging and component engineers appear to successfully follow their main expertise forever. However, there are so many exciting paths to follow, as rewarding as CPMT has been for me, it is time to head off in other directions.

Editor: What's a good book you have read recently?

Dave Palmer: I love books, often haunting libraries and book stores. Recently I was amazed by a book about the artist Hieronymus Bosch. I am currently savoring "War with the Newts" by Karel Capek, the man the coined the term "robots".

Editor: What do you like to do in your spare time?

Dave Palmer: In the hundreds of hours I have saved by not editing the last few issues of the CPMT newsletter, I have had enough spare time to put a new roof on the family home. Civil engineering is hard work but has a very tangible final reward. Vegetable gardening is another hobby, one with very edible rewards.

Editor: Thank you, Dave.

The 56th ECTC
May 30th – June 2nd, 2006

The 56th Electronic Components and Technology Conference (ECTC) was held May 30 through June 2, 2006 at the Sheraton San Diego Hotel and Marina in San Diego, California. This premier international conference brings together the best in packaging, components, and microelectronic systems science, technology, and education. The ECTC is jointly sponsored by the IEEE Components, Packaging and Manufacturing Technology Society (CPMT) and the Electronic Components, Assemblies, and Materials Association (ECA), the electronic components sector of the Electronic Industries Alliance (EIA). ITHERM and ECTC are co-located in even-numbered years to provide attendees with even more opportunities for technical exchange and professional interaction.

The Executive and Program Committees of the 56th ECTC would like extend sincerest thanks to all the authors, presenters, instructors, session co-chairs, program committee members, exhibitors, and our conference and corporate sponsors for making the 56th ECTC so successful.

ECTC consists of three major parts: the technical program, the professional development courses, and the technical exhibit corner. Contributions from more than 20 countries made ECTC a truly global conference. Authors from companies, research institutes, and universities located around the world presented 314 papers at thirty-six oral sessions and two poster sessions to about 1,150 conference participants. Participants caught up with new technology developments and broadened their technical knowledge base in the sixteen professional development courses offered by world-class experts in their fields. The papers and courses covered a wide spectrum of topics, including electronic components, materials, processing, assembly, advanced packaging, system packaging, manufacturing, optoelectronics, interconnections, quality, reliability, modeling and simulation. Emerging technologies topics sessions addressed exciting new developments and applications in biotechnology and nanotechnology. The Technology Corner managed by Bill Moody helped seventy-four leading companies, primarily in the electronics components, materials, and packaging field, showcase their products and services to the engineers attending both ECTC and ITHERM conferences.

The technical program was complemented by three special evening sessions. William Chen, IEEE-CPMT Society President, chaired the panel discussion featuring industry leaders on "3D Packaging and Novel Interconnects." Torsten Wipiejewski, the ECTC Program Chair, chaired the plenary session entitled "Look into the Crystal Ball: Arising New Applications, Technologies and Challenges," which showcased leaders from the semiconductor industry presenting their views on the opportunities and challenges of today's global manufacturing environment." Yoshitaka Fukuoka from Weisti chaired a CPMT technical committee seminar highlighted leading edge developments in high density interconnect technology, "Advanced Substrate Technologies for SiP/SOP."

ECTC *3D Packaging and Novel Interconnects* Panel Speakers

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Relevant Information can be obtained at

www.cpmt.org

ECTC *Look into the Crystal Ball: Arising New Applications, Technologies and Challenges* Plenary Session Speakers

Co-chairs Ron Gedney of iNEMI and M. E. Williams of NIST and moderator H. Leidecker of NASA organized the pre-conference Tin Whiskers Workshop, that provided experimental updates, introduced new analytical tools, and offered insights into tin whisker formation and growth mechanisms. The International CPMT Academic Conference was again held in conjunction with ECTC. This one-day program chaired by Rao Tummala addressed new directions of education in the packaging field.

The ECTC General Chair, Patrick Thompson, hosted the ECTC luncheon. The keynote speaker, Todd Bayer, Chief Engineer of the Mars Reconnaissance Orbiter, spoke about the technology being used in the next phases of Mars exploration.

ECTC Lunch Speaker Todd Bayer

The Vice General Chair, Eric Perfecto, awarded the 2005 Best Paper Awards for the previous year's conference:

- The Best Paper was awarded to M. Kaysar Rahim, Jeffrey C. Suhling, Richard C. Jaeger, and Pradeep Lall from Auburn University for "*Fundamentals of Delamination Initiation and Growth in Flip Chip Assemblies.*"
- Outstanding Paper was awarded to B. E. Lemoff, M. E. Ali, G.Panotopoulos, E. de Groot, G. M. Flower, G. H. Rankin, A. J. Schmit, K. D. Djordjev, M. R.T. Tan, A. Tandon, W. Gong, R. P. Tella, B. Law, and D. W. Dolfi from Agilent Technologies for "*500-Gbps Parallel-WDM Optical Interconnect.*"

ECTC Vice General Chair, Eric Perfecto, Presenting Best Paper Award

- The Best Poster Paper was awarded to I. Ndip, W. John, and H. Reichl from Fraunhofer Institute for "*Effects of Discontinuities and Technological Fluctuations on the RF Performance of BGA Packages.*"
- The Outstanding Poster Paper was awarded to G. Carchon, A Jourdain, and H. A.C. Tilmans from IMEC; O. Vendier from Alcatel; and J. Schoebel from R. Bosch for "*Integration of 0/1-Level Packaged RF-MEMS Devices on MCM-D at Millimeter-Wave Frequencies.*"

The CPMT society hosted Thursday's luncheon, where awards were presented to several ECTC committee members. C.P. Wong was awarded the IEEE Technical Field Award, John Segelken and Connie Swager received the David Feldman Outstanding Contribution Award, and IEEE Fellows were awarded to William Chen, Michael Lebby, Johan Liu, Michael McShane, and Madhavan Swaminathan.

Dr. William T. Chen, IEEE CPMT Society President, presiding over the CPMT Society Luncheon.

Torsten Wipiejewski, moderated the Friday Program Chair's luncheon. The Motorola Packaging Fellowship, a three-year fellowship grant of $21,100 to the student's university, was presented by Andrew Skipor. The winning student was **Arindam Goswami**, University of Maryland for his paper "On Ultra-Fine Leak Detection of Hermitic Wafer Level Packages.".

The Intel Best Student Paper Award, a $2500 cash prize given to the best student presentation in the area on modeling or advance

packaging, was presented by Debendra Mallik. The winning student was Lingbo Zhu of Georgia Institute of Technology for "*In-situ Opening Aligned Carbon Nanotube Films/Arrays for Multichannel Ballistic Transport in Electrical Interconnects.*"

Torsten Wipiejewski, ECTC 2006 Program Chair, Presiding over ECTC Program Chair Luncheon

Andrew Skipor of Motorola Inc. presenting Motorola Packaging Fellowship to Arindam Goswami, Univ of Maryland.

Debendra Mallik of Intel Corporation presenting Intel Best Student Paper Award to Lingbo Zhu of Georgia Institute of Technology

The 57th ECTC will be held from May 29 to June 1, 2007 at John Ascuaga's Nugget in Reno, Nevada. Abstract and course proposal submissions are due by October 15, 2006 and can be submitted on line at **www.ectc.net** starting in mid-August. For additional information, contact the 2007 Program Chair, Rao Bonda, Freescale Semiconductor, Inc., +1-480-413-4511, **rao.bonda@freescale.com**.

The CPMT Society 2006 Award Winners
(continued from Page 1)

Lights! Camera! Action! A Hollywood theme set the stage for this year's CPMT Society Awards luncheon, held during the 56th Electronics Components and Technology Conference (ECTC) in sunny San Diego, California. Almost 800 attendees were on hand to celebrate individuals who personify the goals of the Society as well as the profession itself.

The guests were seated around tables that included "walk of fame" stars highlighting individuals who have made or continue make significant contributions to the electronics and packaging industry. The names of historical pioneers such as Jack Kilby and Gordon Moore were intermingled with today's "stars" such as Yutaka Tsukada and Rao Tummala, demonstrating just how important people are to the profession and to the Society.

William T. Chen, President of the CPMT Society, opened the ceremony with a few words. "The collective work of our industry has contributed to a world driven by transistors and electronics. We have seen great improvements in transportation, medical applications, communications, and other life-affecting industries. These are very good things." said Chen. "And we all stand on the shoulders of brilliant engineers and scientists who came before us, building on their discoveries to make our own research and breakthroughs possible," he added.

Here is a recap of this year's award winners:

The 2006 IEEE Technical Field Award

The *IEEE Components, Packaging and Manufacturing Technology Award* was presented to **C.P. Wong** (Georgia Institute of Technology, USA) for his contributions in advanced polymeric

materials science and processes for highly reliable electronic packages. IEEE-USA President (and former CPMT Society president) **Ralph W. Wyndrum, Jr.** presented the award. Wong's extensive list of accomplishments includes 40 U.S. patents, over 450 published technical papers and numerous other CPMT Society awards. Wong thanked his personal mentors, including **Rao R. Tummala** (also a former CPMT Society president) who brought him to Georgia Tech, and his colleagues and students, whose support and collaboration were essential to his achievements. Always humble, Wong suggested that there were many in attendance equally deserving of the honor. Wong received a certificate, a bronze medal and an honorarium.